

# 300mA CMOS LDO WITH SHUTDOWN, ERROR OUTPUT, AND BYPASS

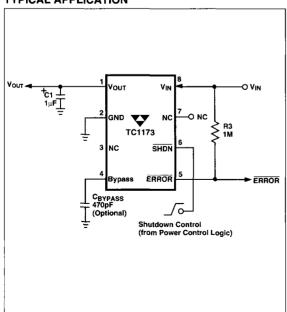
#### **FEATURES**

- Zero Ground Current for Longer Battery Life!
- Very Low Dropout Voltage
- Guaranteed 300mA Output
- Standard or Custom Ouput Voltages
- ERROR Output Can be Used as a Low Battery Detector or Processor Reset Generator
- Power-Saving Shutdown Mode
- Bypass Input for Ultra-Quiet Operation
- Over-Current and Over-Temperature Protection
- Space-Saving MSOP Package Option

#### **APPLICATIONS**

- **■** Battery-Operated Systems
- Portable Computers
- Medical Instruments
- Instrumentation
- Cellular / GSM / PHS Phones
- Linear Post-Regulator for SMPS
- Pagers

#### TYPICAL APPLICATION



#### **GENERAL DESCRIPTION**

The TC1173 is a precision output (typically  $\pm 0.5\%$ ) CMOS low dropout regulator. Total supply current is typically  $50\mu A$  at full load (20 to 60 times lower than in bipolar regulators!).

TC1173 key features include ultra low noise operation (plus optional Bypass input); very low dropout voltage (typically 240mV at full load) and internal feed-forward compensation for fast response to step changes in load. An error output (ERROR) is asserted when the TC1173 is out-of-regulation (due to a low input voltage or excessive output current). ERROR can be set as a low battery warning or as a processor RESET signal (with the addition of an external RC network). Supply current is reduced to 0.05μA (typical) and V<sub>OUT</sub> and ERROR falls to zero when the shutdown input is low.

The TC1173 incorporates both over-temperature and over-current protection. The TC1173 is stable with an output capacitor of only  $1\mu F$  and has a maximum output current of 300mA.

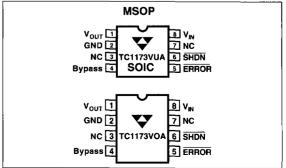
#### ORDERING INFORMATION

Part Number	Package	Junction Temp. Range
TC1173-xxVOA	8-Pin SOIC	- 40°C to +125°C
TC1173-xxVUA	8-Pin MSOP	- 40°C to +125°C

# Available Output Voltages: 2.5, 2.8, 3.0, 3.3, 5.0 xx indicates output voltages

Other output voltages are available. Please contact TelCom Semiconductor for details.

#### PIN CONFIGURATION



TC1173-1 3/30/99

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## TC1173

# ABSOLUTE MAXIMUM RATINGS\*

Input Voltage	7V
Output Voltage	
Power Dissipation	Internally Limited (Note 7)
Operating Temperature	40°C < T1 < 125°C

Storage Temperature ......  $-65^{\circ}$ C to  $+150^{\circ}$ C Maximum Voltage on Any Pin ......  $V_{\text{IN}}$  +0.3V to -0.3V Lead Temperature (Soldering, 10 Sec.) .....  $+300^{\circ}$ C

\*Absolute Maximum Ratings indicate device operation limits beyond damage may occur. Device operation beyond the limits listed in *Electrical Characteristics* is not recommended.

**ELECTRICAL CHARACTERISTICS:**  $V_{IN} = V_{OUT} + 1V$ ,  $I_L = 0.1 \mu A$ ,  $C_L = 3.3 \mu F$ ,  $\overline{SHDN} > V_{IH}$ ,  $T_A = 25 ^{\circ} C$ , unless otherwise noted. **BOLDFACE** type specifications apply for junction temperatures of  $-40 ^{\circ} C$  to  $+125 ^{\circ} C$ 

$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	± 0.5% V <sub>R</sub> +	6.5 V — mA — V - 2.5% ppm/°C
$\begin{array}{cccccccccccccccccccccccccccccccccccc$	V <sub>R</sub> +	V
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	V <sub>R</sub> +	- 2.5%
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$		— ppm/°C
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	0.05 <b>0.</b>	
V <sub>IN</sub> - V <sub>OUT</sub> Dropout Voltage (Note 4)  I <sub>L</sub> = 0.1mA  I <sub>L</sub> = 100mA  I <sub>L</sub> = 300mA  I <sub>SS1</sub> Supply Current SHDN = V <sub>IH</sub>		. <b>35</b> %/V
$\begin{array}{c c} I_L = 100 mA \\ I_L = 300 mA \end{array}$ $\begin{array}{c c} I_{SS1} & Supply Current & \overline{SHDN} = V_{IH} & \end{array}$	0.5 2	2.0 %
301	80 1	30 mV 60 80
	50 9	<b>90</b> μΑ
I <sub>SS2</sub> Shutdown Supply Current SHDN = 0V —	0.05	<b>).5</b> μΑ
PSRR Power Supply Rejection Ratio F <sub>RE</sub> ≤ 1kHz —	60 -	— dB
Iουτ <sub>SC</sub> Output Short Circuit Current V <sub>OUT</sub> = 0V —	550 6	350 mA
ΔV <sub>OUT</sub> ΔP <sub>D</sub> Thermal Regulation Note 5 —	0.04 -	%/W
eN Output Noise $F=1kHz, C_{OUT}=1\mu F,$ — $R_{LOAD}=50\Omega$	260 -	— nV/√Hz
SHDN Input		
V <sub>IH</sub> SHDN Input High Threshold 45		— %V <sub>IN</sub>
V <sub>IL</sub> SHDN Input Low Threshold	_ 1	15 %V <sub>IN</sub>
ERROR Output		
V <sub>MIN</sub> Minimum Operating Voltage 1.0		v
V <sub>OL</sub> Output Logic Low Voltage 1mA Flows to ERROR —	- 4	<b>100</b> mV
V <sub>TH</sub> ERROR Threshold Voltage — 0.9	95 x V <sub>R</sub> -	_ v
V <sub>HYS</sub> ERROR Positive Hysteresis Note 7 —		

NOTES: 1. V<sub>R</sub> is the user-programmed regulator output voltage setting.

2.  $T_C V_{OUT} = (V_{OUT_{MAX}} - V_{OUT_{MIN}}) \times 10^6$ 

VOUT X AT

- 3. Regulation is measured at a constant junction temperature using low duty cycle pulse testing. Load regulation is tested over a load range from 0.1mA to the maximum specified output current. Changes in output voltage due to heating effects are covered by the thermal regulation specification.
- 4. Dropout voltage is defined as the input to output differential at which the output voltage drops 2% below its nominal value measured at a 1V differential.
- Thermal Regulation is defined as the change in output voltage at a time T after a change in power dissipation is applied, excluding load
  or line regulation effects. Specifications are for a current pulse equal to I<sub>LMAX</sub> at V<sub>IN</sub> = 6V for T = 10msec.
- 6. The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature, and the thermal resistance from junction-to-air (i.e. T<sub>A</sub>, T<sub>J</sub>, θ<sub>JA</sub>). Exceeding the maximum allowable power dissipation causes the device to initiate thermal shutdown. Please see *Thermal Considerations* section of this data sheet for more details.
- 7. Hysteresis voltage is referenced to V<sub>R</sub>.

#### **DETAILED DESCRIPTION**

The TC1173 is a fixed output, low drop-out regulator. Unlike bipolar regulators, the TC1173 supply current does not increase with load current. In addition, V<sub>OUT</sub> remains stable and within regulation at very low load currents (an important consideration in RTC and CMOS RAM battery back-up applications). TC1173 pin functions are detailed below:

#### PIN DESCRIPTIONS

Pin No.	Symbol	Description
1	Vout	Regulated voltage output
2	GND	Ground terminal
3	NC	No connect
4	Bypass	Reference bypass input. Connecting a 470pF to this input further reduces output noise.
5	ERROR	Out-of-Regulation Flag. (Open drain output). This output goes low when V <sub>OUT</sub> is out-of-tolerance by approximately –5%.
6	SHDN	Shutdown control input. The regulator is fully enabled when a logic high is applied to this input. The regulator enters shutdown when a logic low is applied to this input. During shutdown, output voltage falls to zero and supply current is reduced to under 1 microamp (typical).
7	NC	No connect
8	VIN	Unregulated supply input

Figure 1 shows a typical application circuit. The regulator is enabled any time the shutdown input (SHDN) is above  $V_{IH}$ , and shutdown (disabled) when SHDN is at or below  $V_{IL}$ . SHDN may be controlled by a CMOS logic gate, or I/O port of a microcontroller. If the SHDN input is not required, it should be connected directly to the input supply. While in shutdown, supply current decreases to  $0.05\mu A$  (typical),  $V_{OUT}$  falls to zero and ERROR is disabled.

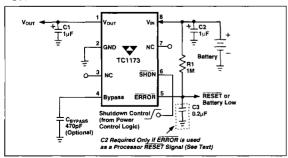


Figure 1: Typical Application Circuit

## **ERROR** Output

ERROR is driven low whenever V<sub>OUT</sub> falls out of regulation by more than – 5% (typical). This condition may be caused by low input voltage, output current limiting, or thermal limiting.

The ERROR threshold is 5% below rated  $V_{OUT}$  regardless of the programmed output voltage value (e.g., ERROR =  $V_{OL}$  at 4.75V (typ) for a 5.0V regulator and 2.85V (typ) for a 3.0V regulator). ERROR output operation is shown in Figure 2. Note that ERROR is active when  $V_{OUT}$  is at or below  $V_{TH}$ , and inactive when  $V_{OUT}$  is above  $V_{TH}$  +  $V_{H}$ .

As shown in Figure 1,  $\overline{ERROR}$  can be used as a battery low flag, or as a processor  $\overline{RESET}$  signal (with the addition of timing capacitor C2). R1 x C3 should be chosen to maintain  $\overline{ERROR}$  below  $V_{IH}$  of the processor  $\overline{RESET}$  input for at least 200msec to allow time for the system to stabilize. Pull-up resistor R1 can be tied to  $V_{OUT}$ ,  $V_{IN}$  or any other voltage less than  $(V_{IN}+0.3V_{.})$ 

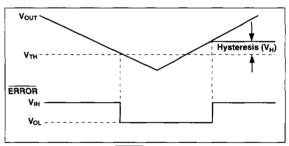


Figure 2: ERROR Output Operation

#### **Output Capacitor**

A  $1\mu F$  (min) capacitor from  $V_{OUT}$  to ground is recommended. The output capacitor should have an effective series resistance of  $5\Omega$  or less, and a resonant frequency above 1MHz. A  $1\mu F$  capacitor should be connected from  $V_{IN}$  to GND if there is more than 10 inches of wire between the regulator and the AC filter capacitor, or if a battery is used as the power source. Aluminum electrolytic or tantalum capacitor types can be used. (Since many aluminum electrolytic capacitors freeze at approximately  $-30^{\circ}C$ , solid tantalums are recommended for applications operating below  $-25^{\circ}C$ .) When operating from sources other than batteries, supplynoise rejection and transient response can be improved by increasing the value of the input and output capacitors and employing passive filtering techniques.

#### **Bypass Input**

A 470pF capacitor connected from the Bypass input to ground reduces noise present on the internal reference, which in turn significantly reduces output noise. If output noise is not a concern, this input may be left unconnected.

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## TC1173

Larger capacitor values may be used, but results in a longer time period to rated output voltage when power is initially applied.

#### Thermal Considerations

#### Thermal Shutdown

Integrated thermal protection circuitry shuts the regulator off when die temperature exceeds 150°C. The regulator remains off until the die temperature drops to approximately 140°C.

#### **Power Dissipation**

The amount of power the regulator dissipates is primarily a function of input and output voltage, and output current. The following equation is used to calculate worst case *actual* power dissipation:

Where:

P<sub>D</sub> = worst case actual power dissipation

 $V_{INMAX} = maximum voltage on V_{IN}$ 

Voυτ<sub>MIN</sub> = minimum regulator output voltage

ILOADMAX = maximum output (load) current

#### Equation 1.

The maximum *allowable* power dissipation (Equation 2) is a function of the maximum ambient temperature ( $T_{AMAX}$ ), the maximum allowable die temperature ( $125^{\circ}C$ ), and the thermal resistance from junction-to-air ( $\theta_{JA}$ ). The SOIC-8 package has a  $\theta_{JA}$  of approximately **160°C/Watt**, while the MSOP-8 package has a  $\theta_{JA}$  of approximately **200°C/Watt**, both when mounted on a single layer FR4 dielectric copper clad PC board.

$$P_{DMAX} = (T_{JMAX} - T_{AMAX})$$

$$\theta_{JA}$$

Where all terms are previously defined.

#### Equation 2.

Equation 1 can be used in conjunction with Equation 2 to ensure regulator thermal operation is within limits. For example:

GIVEN:

 $V_{INMAX} = 3.0V \pm 10\%$   $V_{OUT_{MIN}} = 2.7V \pm 0.5\%$  $I_{LOAD} = 250mA$ 

T<sub>AMAX</sub> = 55°C MSOP-8 Package

FIND:

1. Actual power dissipation

2. Maximum allowable dissipation.

Actual power dissipation:

 $P_D \approx (V_{INMAX} - V_{OUT_{MIN}})I_{LOAD_{MAX}}$ = [(3.0 x 1.1) - (2.7 x .995)]250 x 10<sup>-3</sup> = 155mW

Maximum allowable power dissipation:

$$P_D \approx \underbrace{\left(TJ_{MAX} - TA_{MAX}\right)}_{\theta_{JA}}$$

= <u>(125 – 55)</u> 200

= 350mW

In this example, the TC1173 dissipates a maximum of only 155mW; far below the allowable limit of 350mW. In a similar manner, Equation 1 and Equation 2 can be used to calculate maximum current and/or input voltage limits. For example, the maximum allowable  $V_{IN}$  is found by substituting the maximum allowable power dissipation of 350mW into Equation 1, from which  $V_{INMAX} = 4.1V$ .

#### **Layout Considerations**

The primary path of heat conduction out of the package is via the package leads. Therefore, layouts having a ground plane, wide traces at the pads, and wide power supply bus lines combine to lower  $\theta_{\text{JA}}$  and, therefore, increase the maximum allowable power dissipation limit.

# 5

### TYPICAL CHARACTERISTICS

